

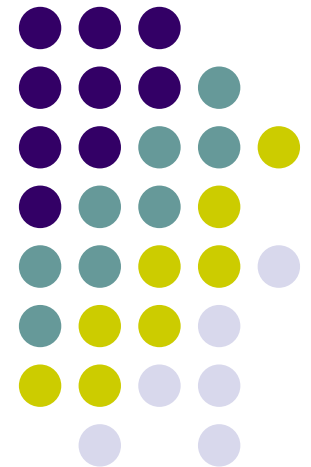
# Preparation of Nanostructures I: Next Generation Lithography

---

MB-JASS 2006

Georg Dürr

Technical University Munich



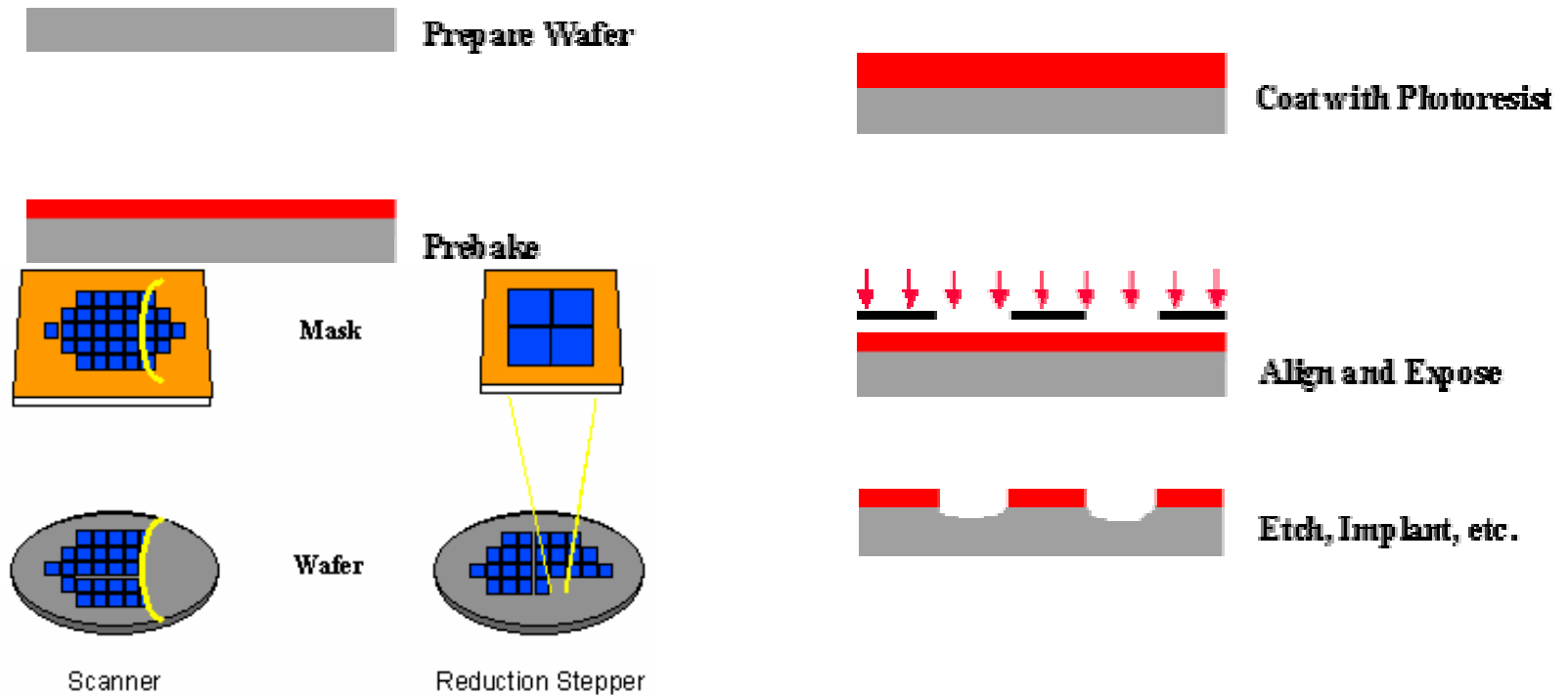


# Agenda

- **State-of-the-art lithography**
- Advanced optical lithography
  - Liquid immersion lithography
  - Hybrid lithography
  - EUV lithography
- Nanoimprint lithography
- Two-photon lithography



# State-of-the-art lithography



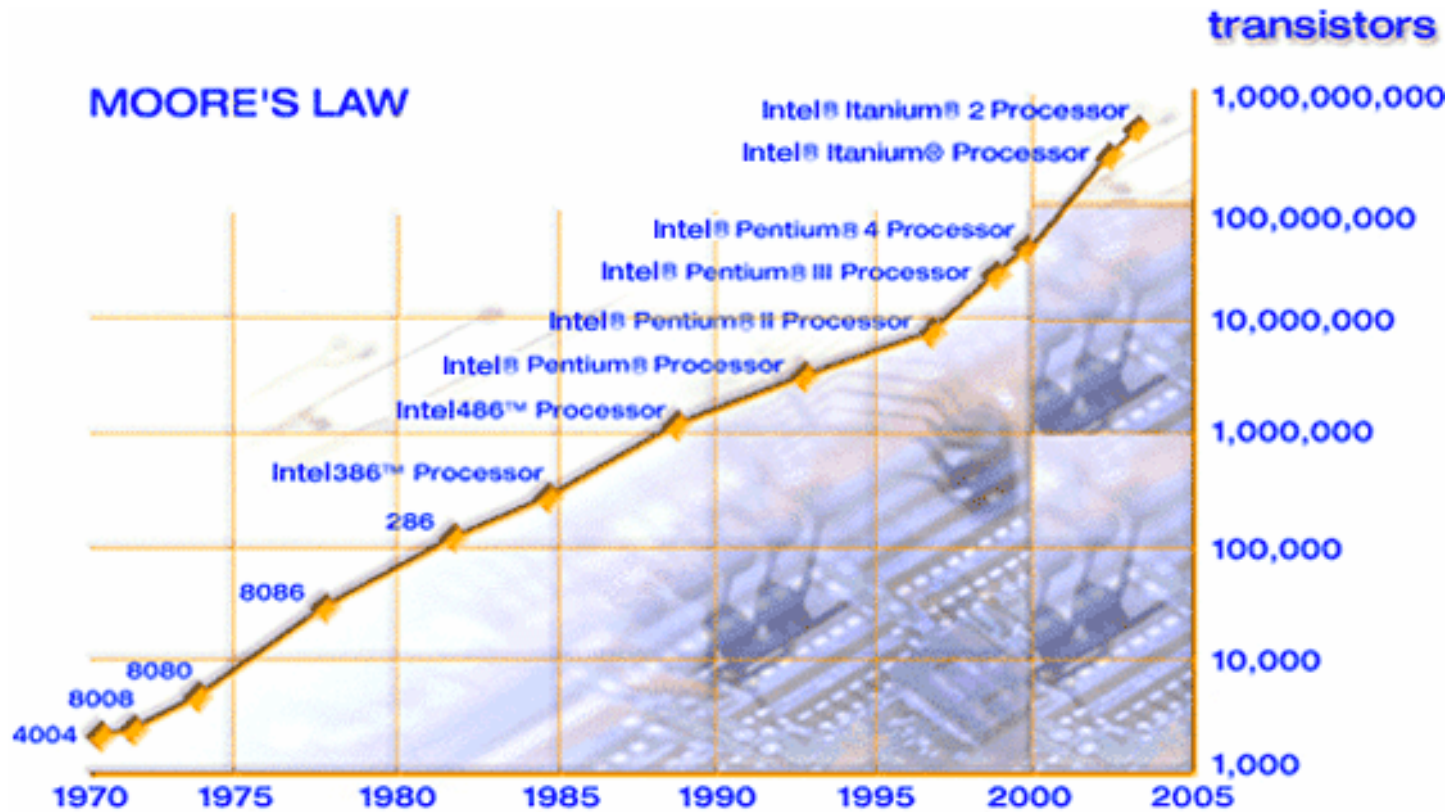
GD1

nano:= <100nm @2003  
Georg Dürr, 05/03/2006

# State-of-the-art lithography



- Historical overview: Moore's Law

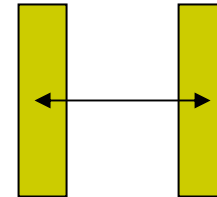




# State-of-the-art lithography

- 193-nm light source: ArF excimer lasers

- Feature size: 65 nm half pitch



- Critical tools: phase-shifting masks, proximity corrections
- Materials: Optics, resists

# State-of-the-art lithography

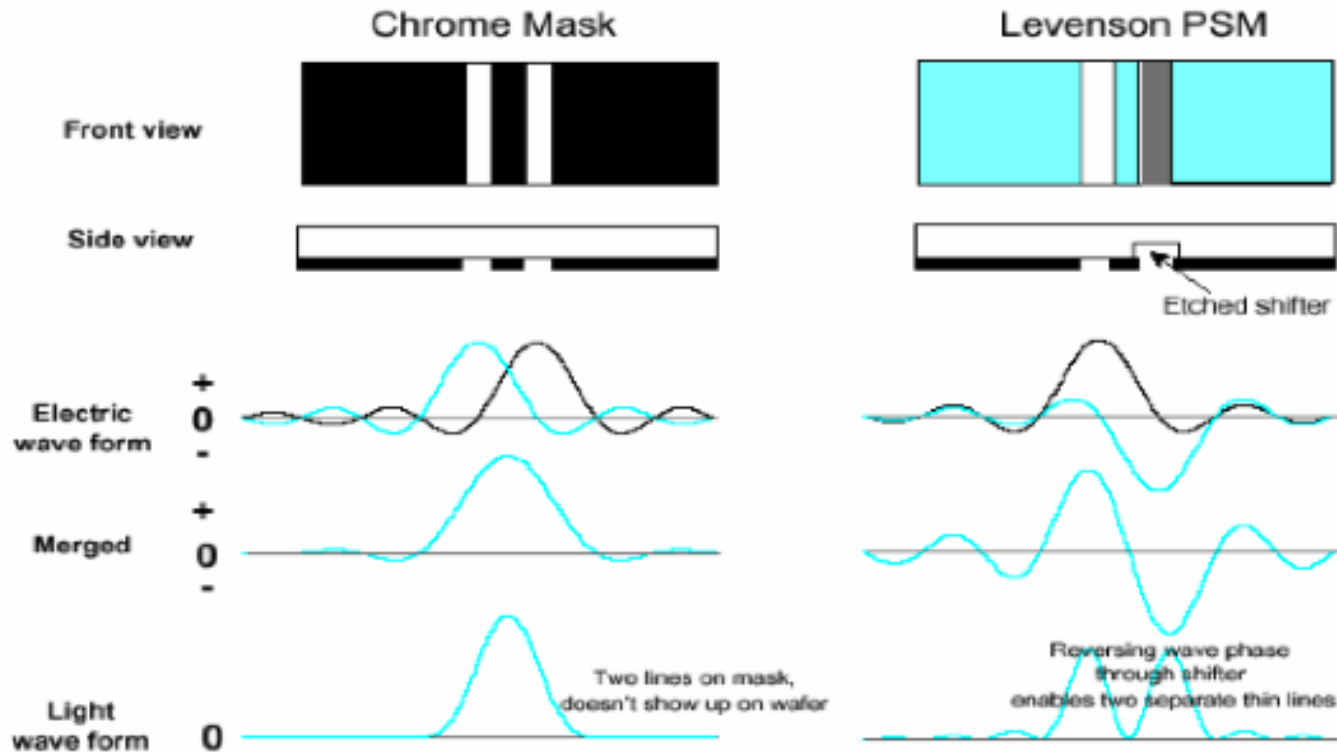


- Rayleigh-criterion: 
$$W = \frac{k\lambda}{NA}$$
- $k$ : empirical constant
- $NA = n \sin \theta$
  
- → Enhance quality of optical instruments ( $k$ )
- → reduce wave length  $\lambda$
- → increase  $NA$

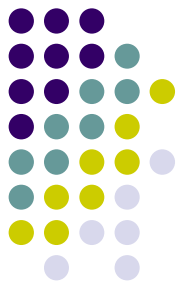


# State-of-the-art lithography

## Mechanism of Levenson Phase Shift Mask





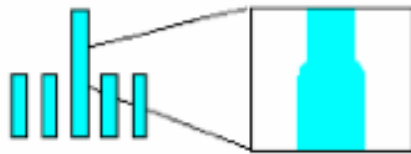


# State-of-the-art lithography

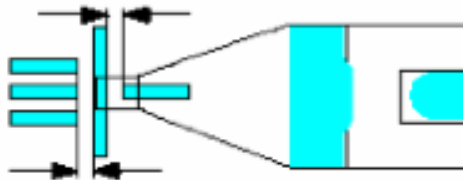
## Optical Proximity Effect and Optical Proximity Corrections

How optical proximity effects effects patterns

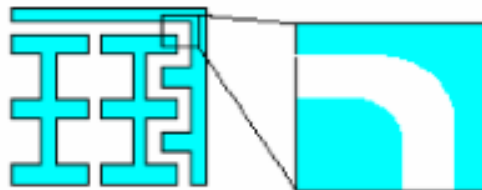
Line width warped due to optical proximity



Line-end shrink

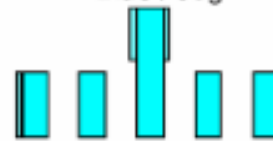


Rounding corners

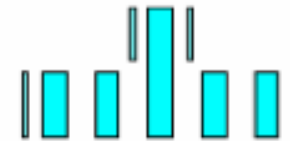


How to correct distorted area (OPC)

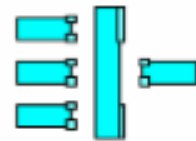
Bias / Jog



Assist bar



Serif / Jog



Hammerhead



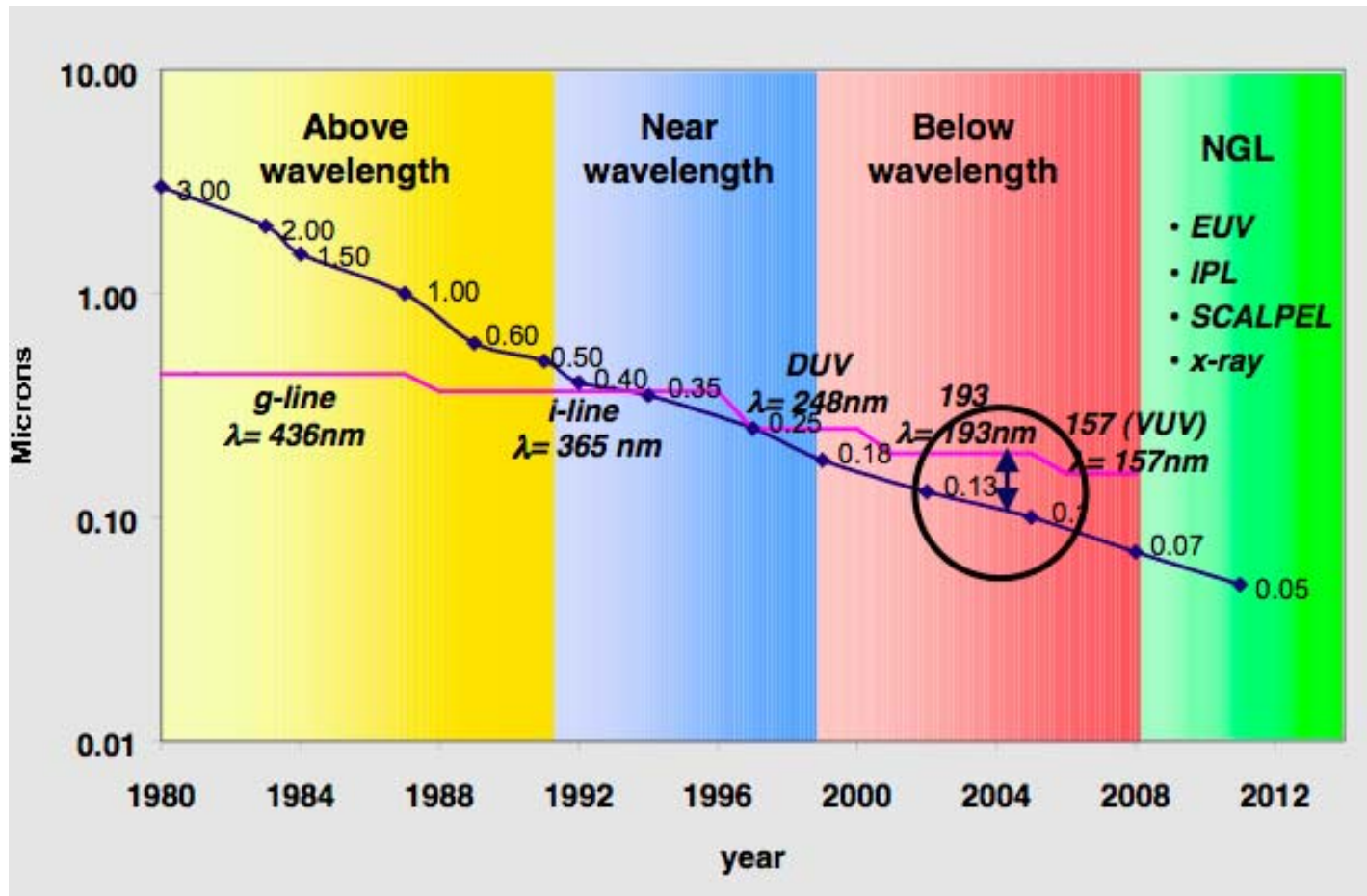
Extension / Jog



Outer / Inner Serif



# State-of-the-art lithography





# Agenda

- State-of-the-art lithography
- **Advanced optical lithography**
  - Liquid immersion
  - Hybrid lithography
  - EUV
- Nanoimprint lithography
- Two-photon lithography

# Advanced optical lithography



- Reduce wavelength
- Reduce wavelength of light source
- Reduce effective wavelength (immersion)

# Advanced optical lithography



- Proposed new light source: 157-nm F2 lasers
- Development of many new materials
- Lack of photo mask protection
- Lack of high-yield growth of crystals
- Improved 193-nm developed instead



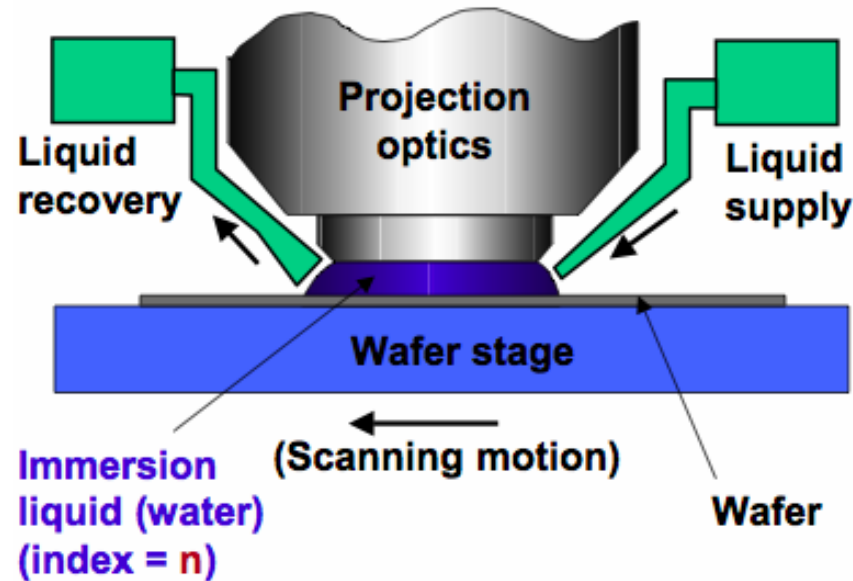
# Agenda

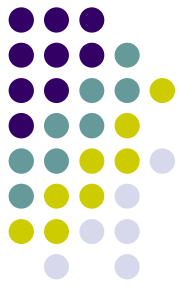
- State-of-the-art lithography
- **Advanced optical lithography**
  - **Liquid immersion**
  - Hybrid lithography
  - EUV
- Nanoimprint lithography
- Two-photon lithography

# Liquid immersion lithography



- Improved 193-nm technology





# Liquid immersion lithography

- Advantages of liquid immersion:
- keep investments in steppers, masks etc.
- Reduction of effective wavelength:

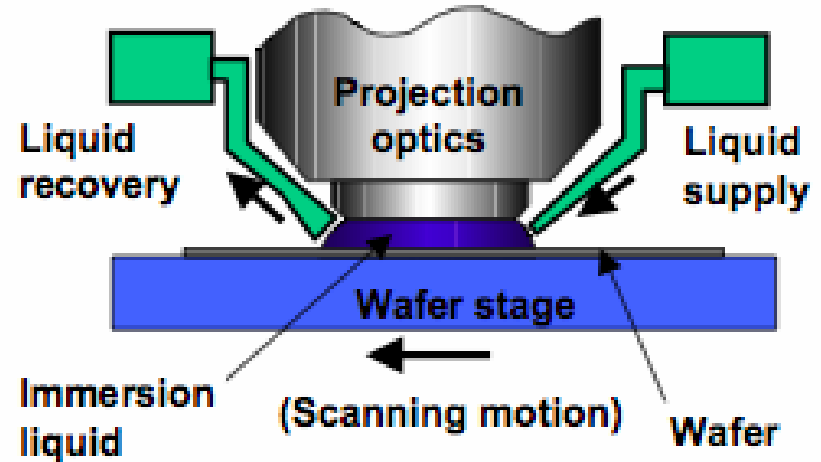
	medium	n	$\lambda/n$	ratio
<b>ArF dry</b>	<b>Air</b>	<b>1.0</b>	<b>193nm</b>	<b>1.00</b>
<b>F2 dry</b>	<b>N<sub>2</sub></b>	<b>1.0</b>	<b>157nm</b>	<b>0.81</b>
<b>ArF immersion</b>	<b>H<sub>2</sub>O</b>	<b>1.44</b>	<b>134nm</b>	<b>0.69</b>
<b>F2 immersion</b>	<b>PFPE</b>	<b>1.37</b>	<b>115nm</b>	<b>0.60</b>



# Liquid immersion lithography



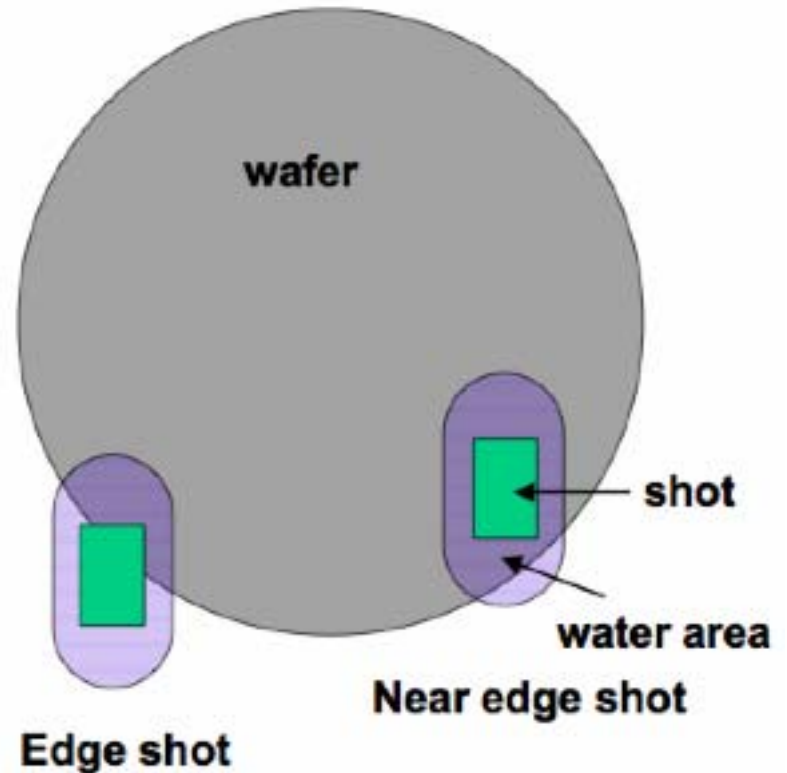
- Liquid immersion lithography: challenges
- Water fill:  
Local fill:





# Liquid immersion lithography

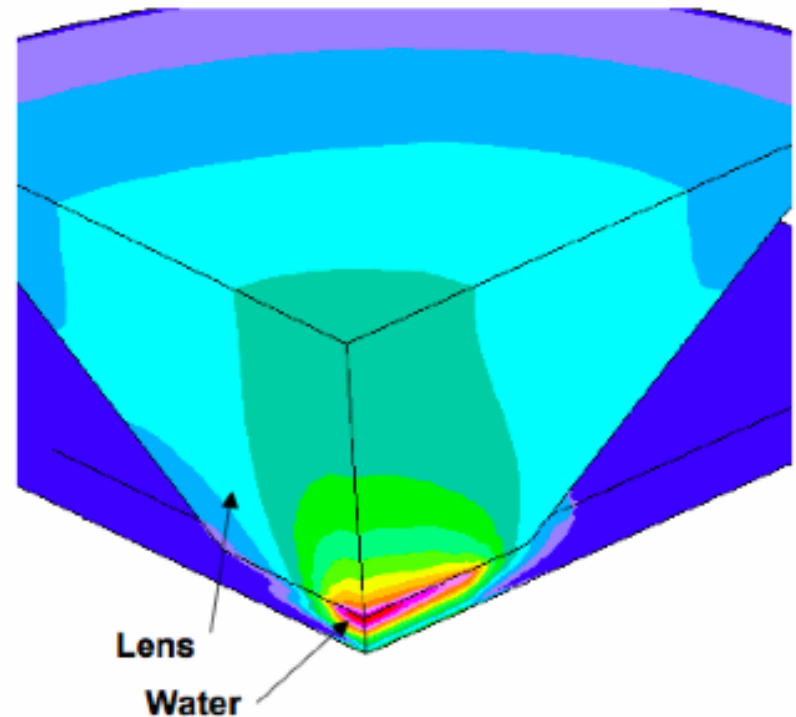
- Liquid immersion lithography: challenges
- Water fill
- Edge shot:



# Liquid immersion lithography



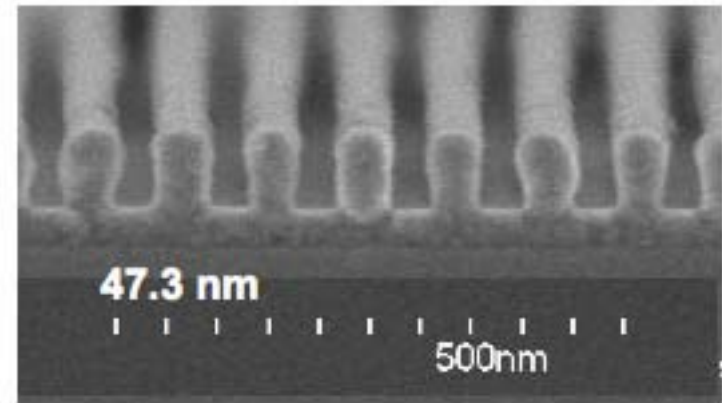
- Liquid immersion lithography: challenges
- Water fill
- Edge shot
- Thermal aberration:



# Liquid immersion lithography



- Liquid immersion lithography: challenges
- Water fill
- Edge shot
- Thermal aberration
- Resist availability:

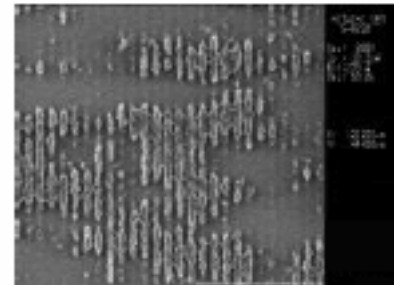
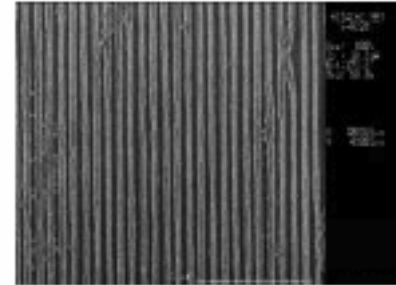


**45nm half pitch**

# Liquid immersion lithography



- Liquid immersion lithography: challenges
- Water fill
- Edge shot
- Thermal aberration
- Resist availability:



# Liquid immersion lithography



- Liquid immersion lithography: challenges
  - Water fill
  - Edge shot
  - Thermal aberration
  - Resist availability
  - Leaching ?
  - Small bubbles ?
  - Water contamination ?

# Liquid immersion lithography



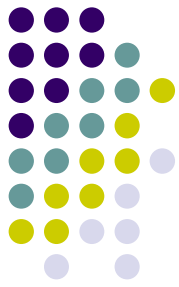
- Liquid immersion lithography:
- AMD, IBM: **wet** 193 nm for 65 nm
- Intel: **dry** 193 nm down to 45 nm, switching directly to EUV sources
- IBM demonstrated 22 nm with **dry** 193 nm

# Liquid immersion lithography



- Next step: 32 nm with 193-nm light
- High-index fluids,  $n=1.9$
- E.g. hydrocarbon fluids,  $n=1.6$
- Or take wet 157-nm
- And take up additional challenges!





# Agenda

- State-of-the-art lithography
- **Advanced optical lithography**
  - Liquid immersion
  - **Hybrid lithography**
  - EUV
- Nanoimprint lithography
- Two-photon lithography



# Hybrid lithography

- A different approach: using interference
- Optical grid
- High throughput
- Creating only periodic grid structures
- Up to 32 nm structures
- Hybrid lithography

# Advanced optical lithography



- Sooner or later: reduce the wavelength
- Extreme UV (EUV)
- Electron beam
- Projection electron beam (SCALPEL)
- Ion Beam (IPL)
- X-ray

# Agenda



- State-of-the-art lithography
- **Advanced optical lithography**
  - Liquid immersion
  - Hybrid lithography
  - **EUV**
- Nanoimprint lithography
- Two-photon lithography



# EUV lithography

- Overview

<b>Pitch/2 (nm)</b>	<b><math>k_1</math></b>	<b><math>\lambda</math> (nm)</b>	<b>NA</b>
32	0.30	193	1.81
32	0.30	157	1.47
32	<b>0.59</b>	13.5	0.25

# EUV lithography

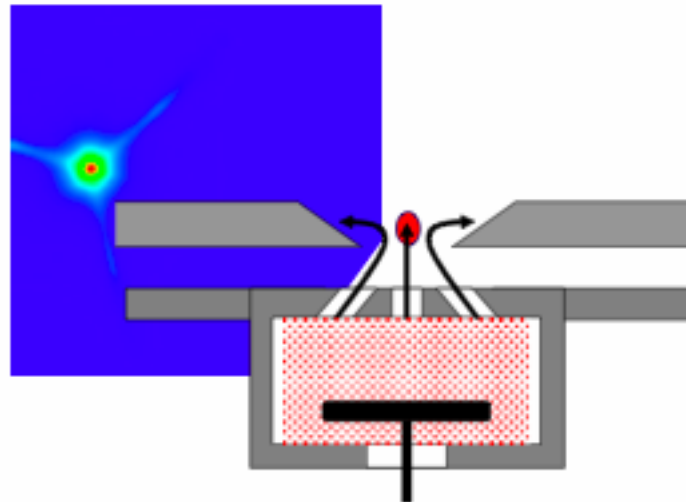


- Requirements
- Wavelength: 13.5 nm
- Power in focus: 115 W
- Condenser lifetime: min. 30,000 hrs.
- Energy stability,  $\pm 0,3\%$

# EUV lithography

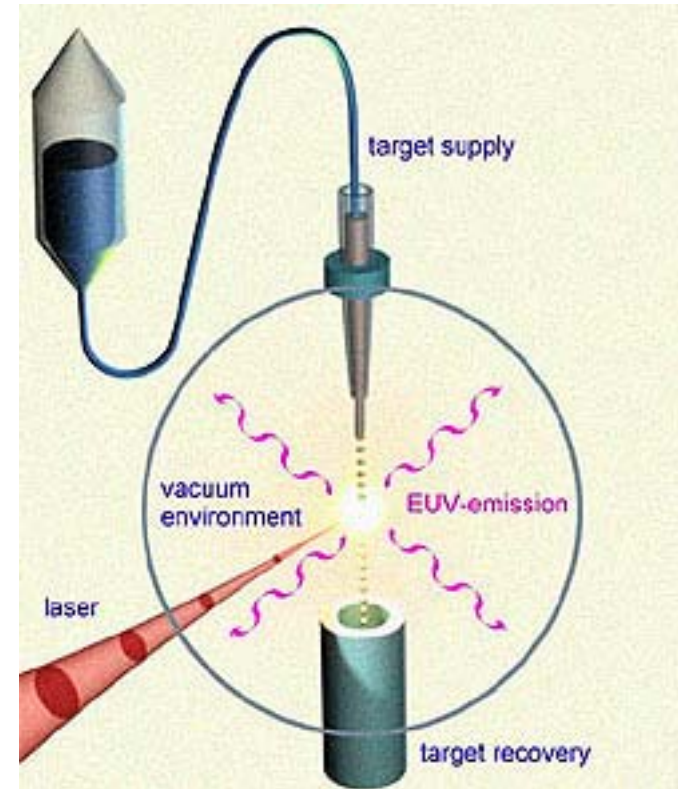


- Sources:
- Gas discharge Plasma:



# EUV lithography

- Sources:
- Laser produced plasma:





# EUV lithography

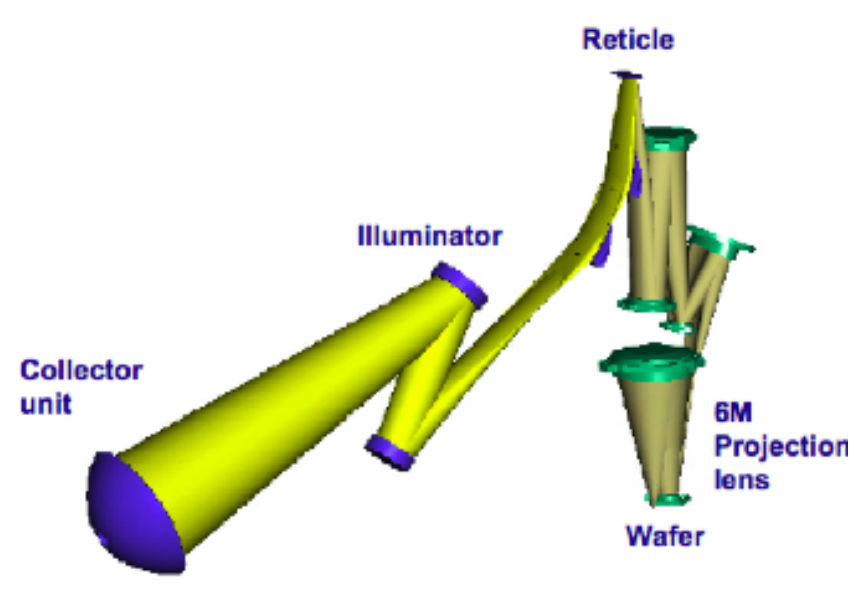


- Sources:
- GDPP: preferred - contamination, power, lifetime still insufficient
- LPP: costly

# EUV lithography



- Optics:
- Mirror optics required
- Enhance reflectivity (70%)
- Contamination
- Perfect surfaces
- Lifetime



# EUV lithography



- More issues:
- Mask handling
- Resist resolution
- ... Yet to be resolved

# EUV lithography



- Announced in 1997 by Intel, Motorola, AMD:  
in use for production by 2004
- Today: Intel, ASML plan introduction in 2009



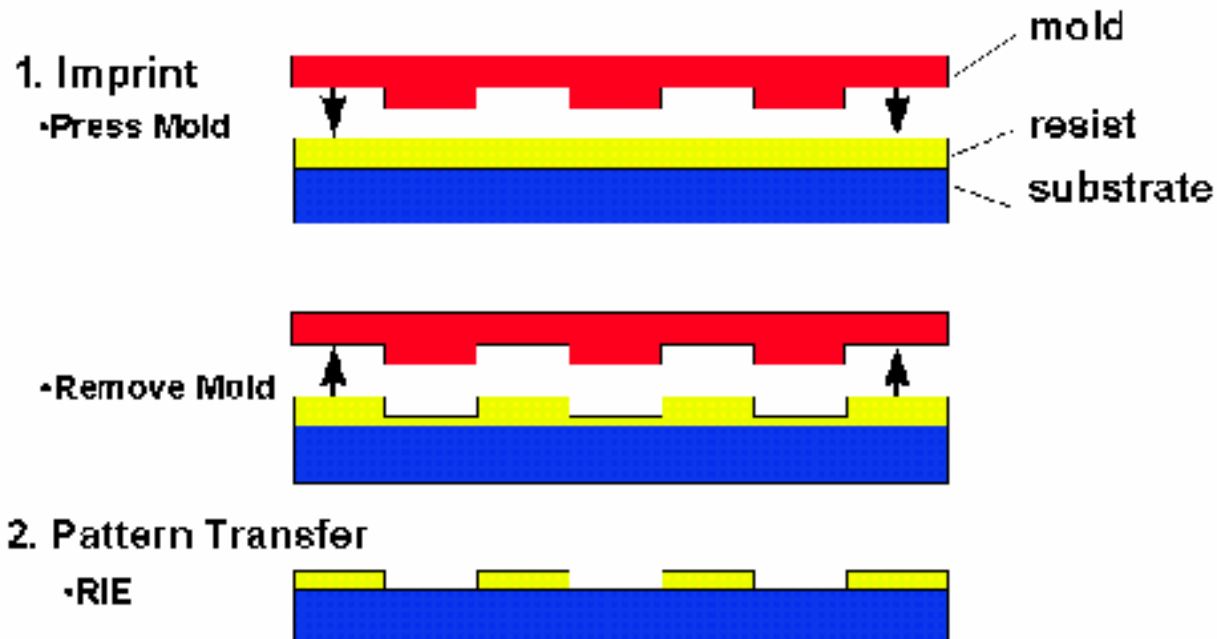
# Agenda

- State-of-the-art lithography
- Advanced optical lithography
  - Liquid immersion
  - Hybrid lithography
  - EUV
- **Nanoimprint lithography**
- Two-photon lithography



# Nanoimprint lithography

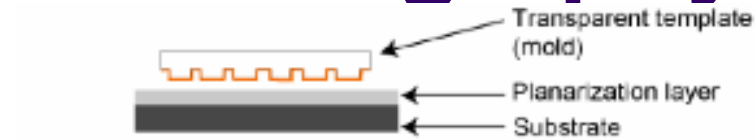
- Thermal NIL





# Nanoimprint lithography

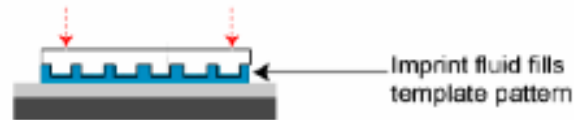
- UV-NIL



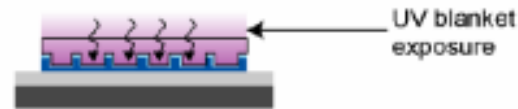
Step 1: Orient template and substrate



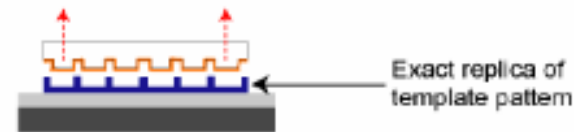
Step 2: Dispense drops of liquid imprint resist



Step 3: Lower template and fill pattern



Step 4: Polymerize imprint fluid with UV exposure



Step 5: Separate template from substrate

# Nanoimprint lithography

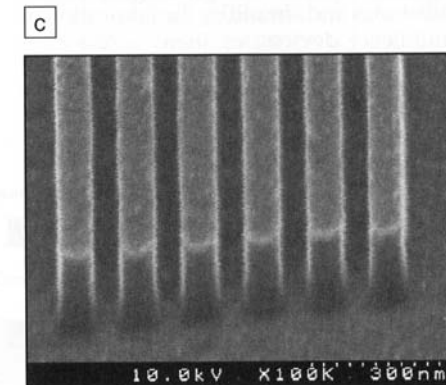
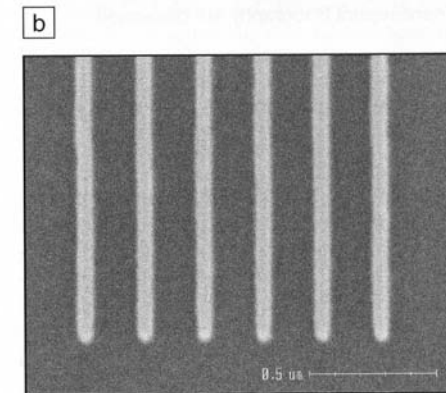
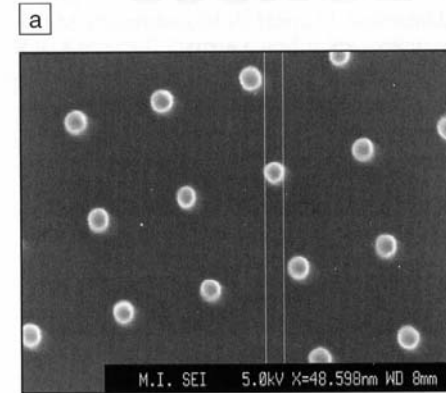


- Why UV-NIL?
- Lower forces: 100 kPa instead of 500-5000 kPa
- No heating, no cooling
- Longer lifetime, faster imprint
- Sub 5-nm demonstrated



# Nanoimprint

- What can you do with NIL?
- MOSFET
- TFT
- Microfluidics



# Nanoimprint lithography



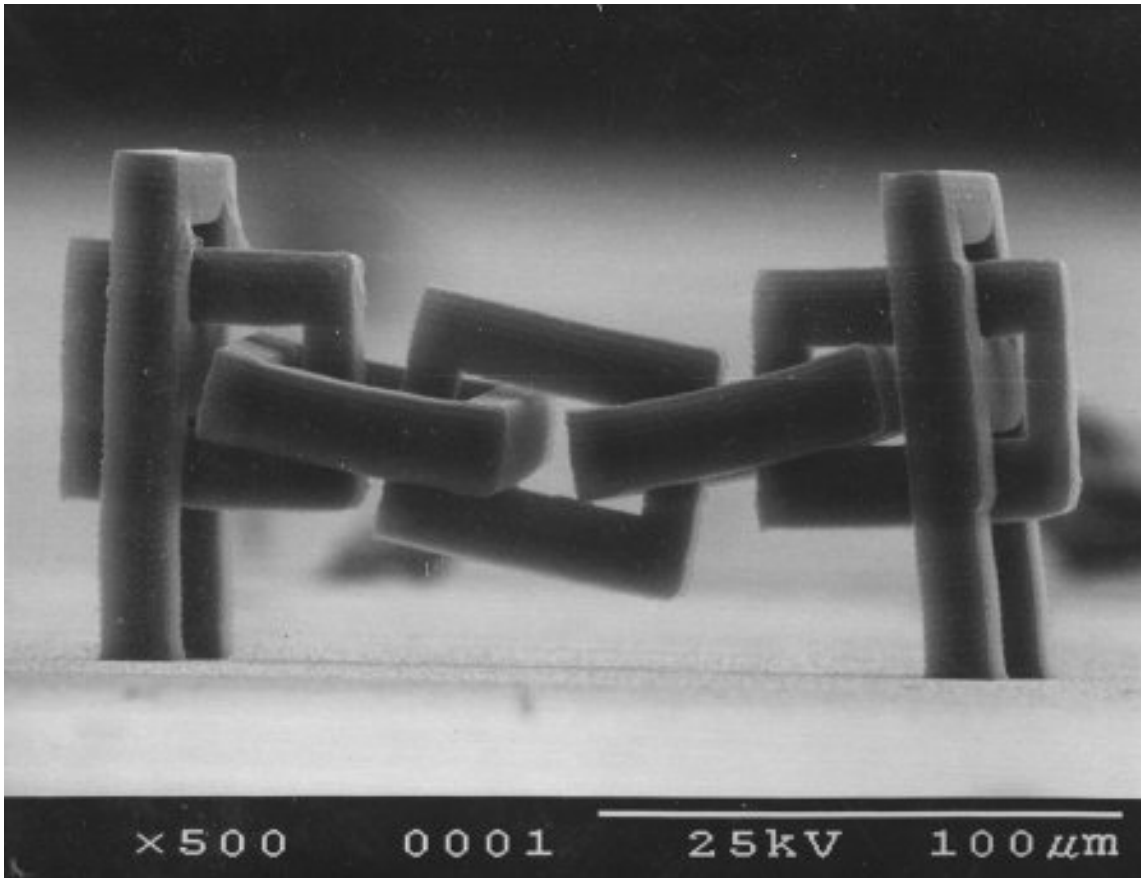
- Issues
- Production of templates
- Defect control
- Small throughput
- Materials
- Possibly 10 nm with self assembled nanostructures  
... Far beyond 2010



# Agenda

- State-of-the-art lithography
- Advanced optical lithography
  - Liquid immersion
  - Hybrid lithography
  - EUV
- Nanoimprint lithography
- **Two-photon lithography**

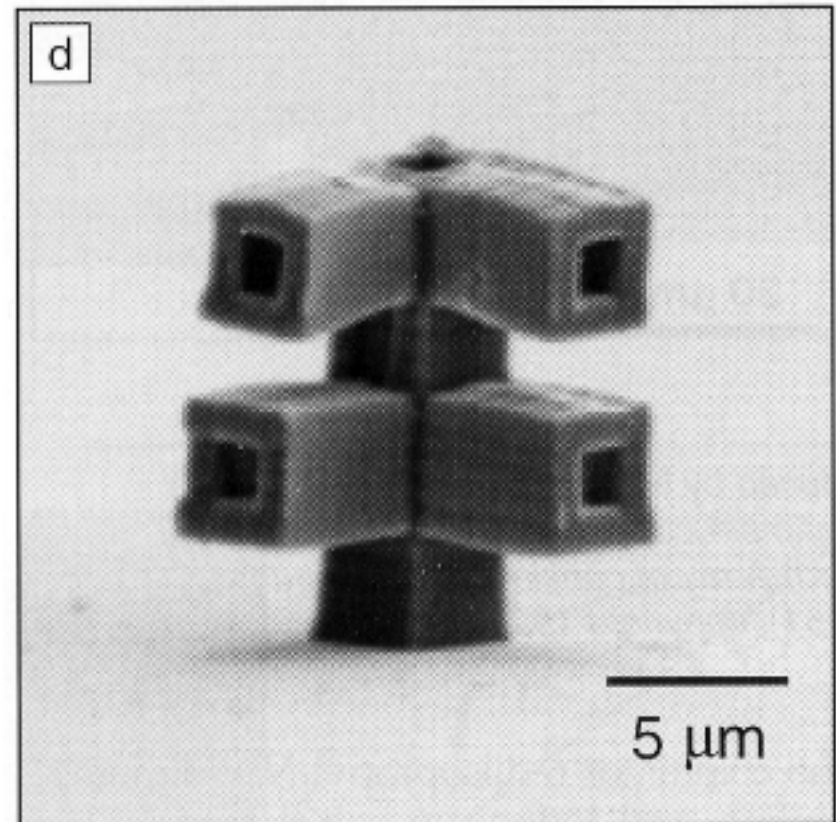
# Two-photon lithography





# Two-photon lithography

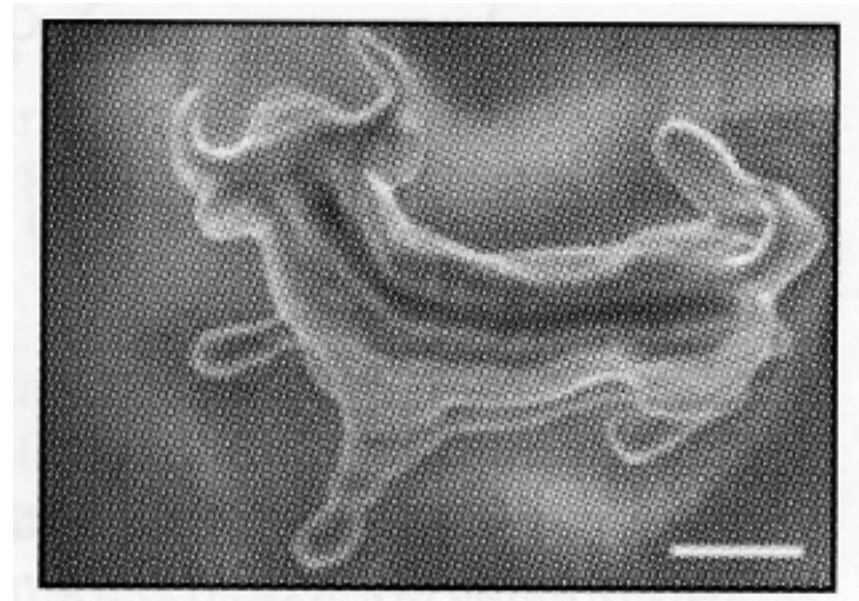
- Chromophores with nonlinear absorbance
- Absorbance only inside the focal point
- Femtosecond laser beam
- E.g. polymerization in close proximity
- Order of 250 nm in practice
- Positive working systems realized





# Two-photon lithography

- Applications
- Controlled photonic crystals
- Using even doped materials, metals
- MEMS / NEMS
- Protein matrices as drug delivery devices





# Agenda

- State-of-the-art lithography
- Advanced optical lithography
  - Liquid immersion
  - Hybrid lithography
  - EUV
- Nanoimprint lithography
- Two-photon lithography